

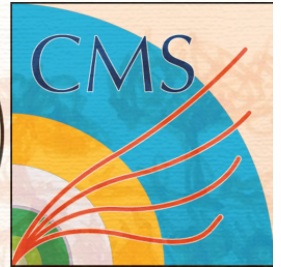


Testing the new electronics of the CMS phase I upgrade pixel detector

Riccardo Del Burgo on behalf of CMS

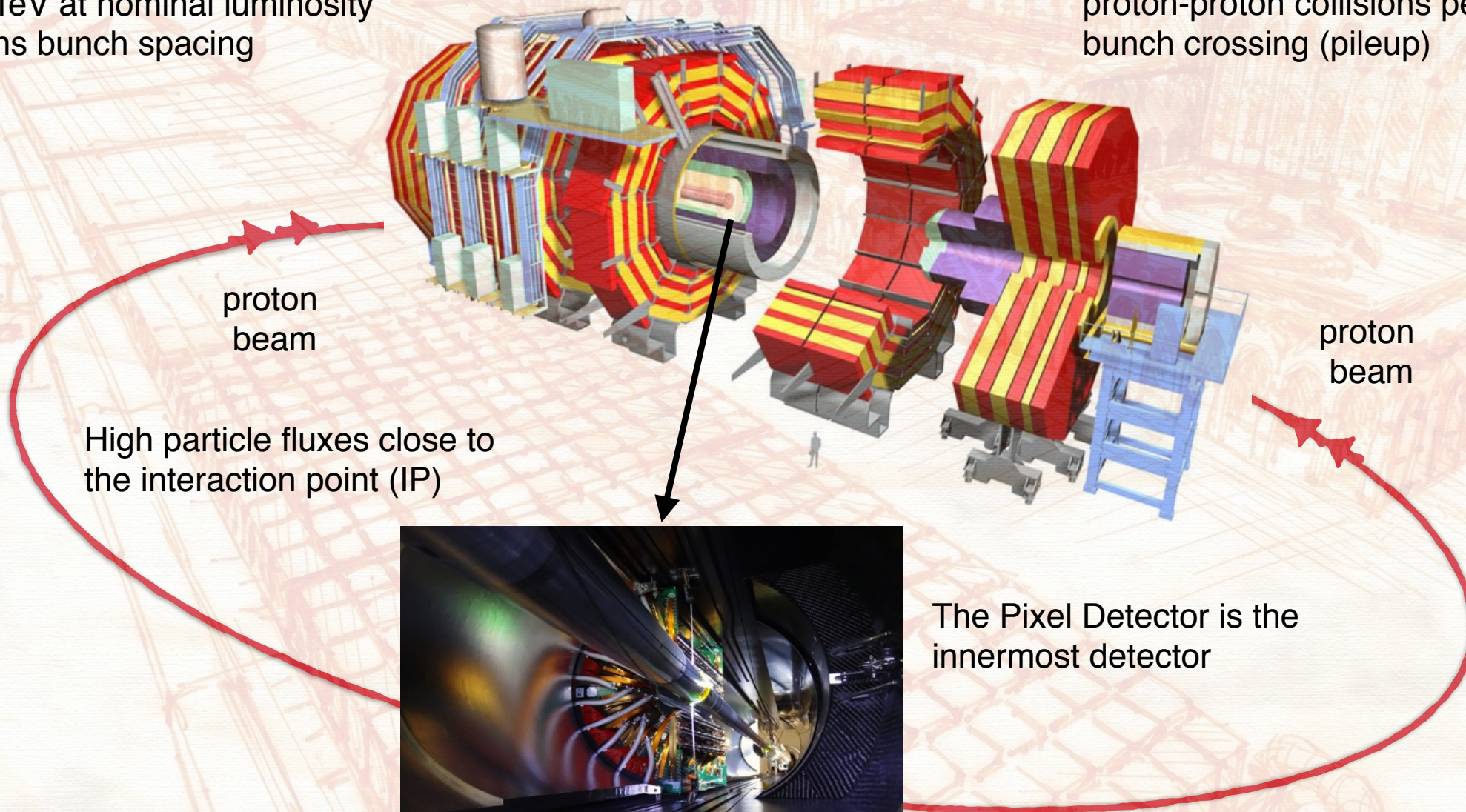
PhD seminar 24 November 2016

LHC and CMS



p-p collision
13 TeV at nominal luminosity
25 ns bunch spacing

expected average of ~ 25
proton-proton collisions per
bunch crossing (pileup)



High particle fluxes close to
the interaction point (IP)

The Pixel Detector is the
innermost detector

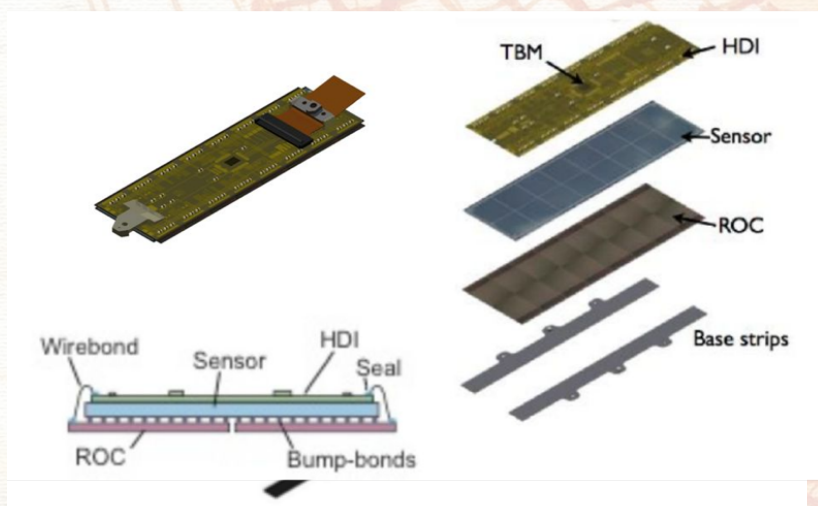
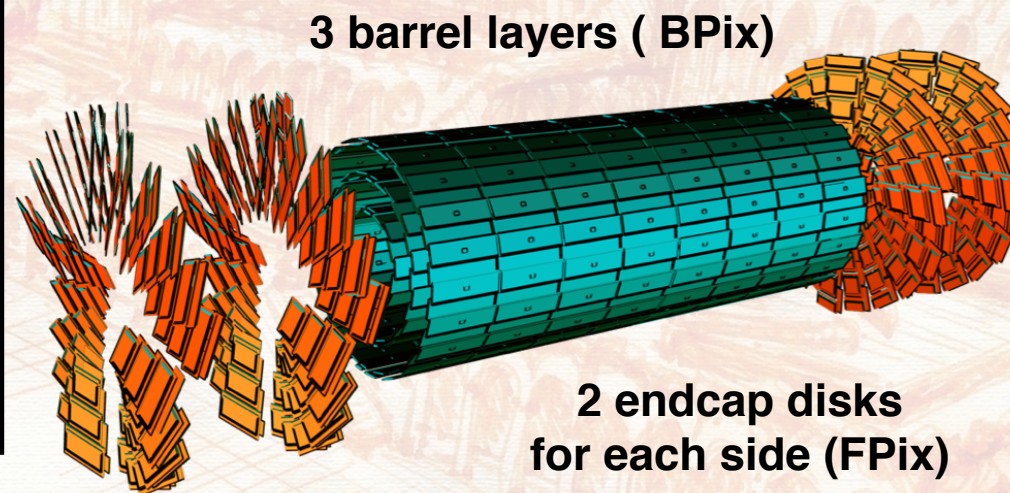


CMS Pixel Detector



Feature and purpose:

- Reconstruct the track of particles with high precision (res $\sim 10\mu\text{m}$)
- High tracking efficiency
- Efficient tagging of long lived particle
- Primary vertex and impact parameter measurement
- Provide seeds for track reconstruction



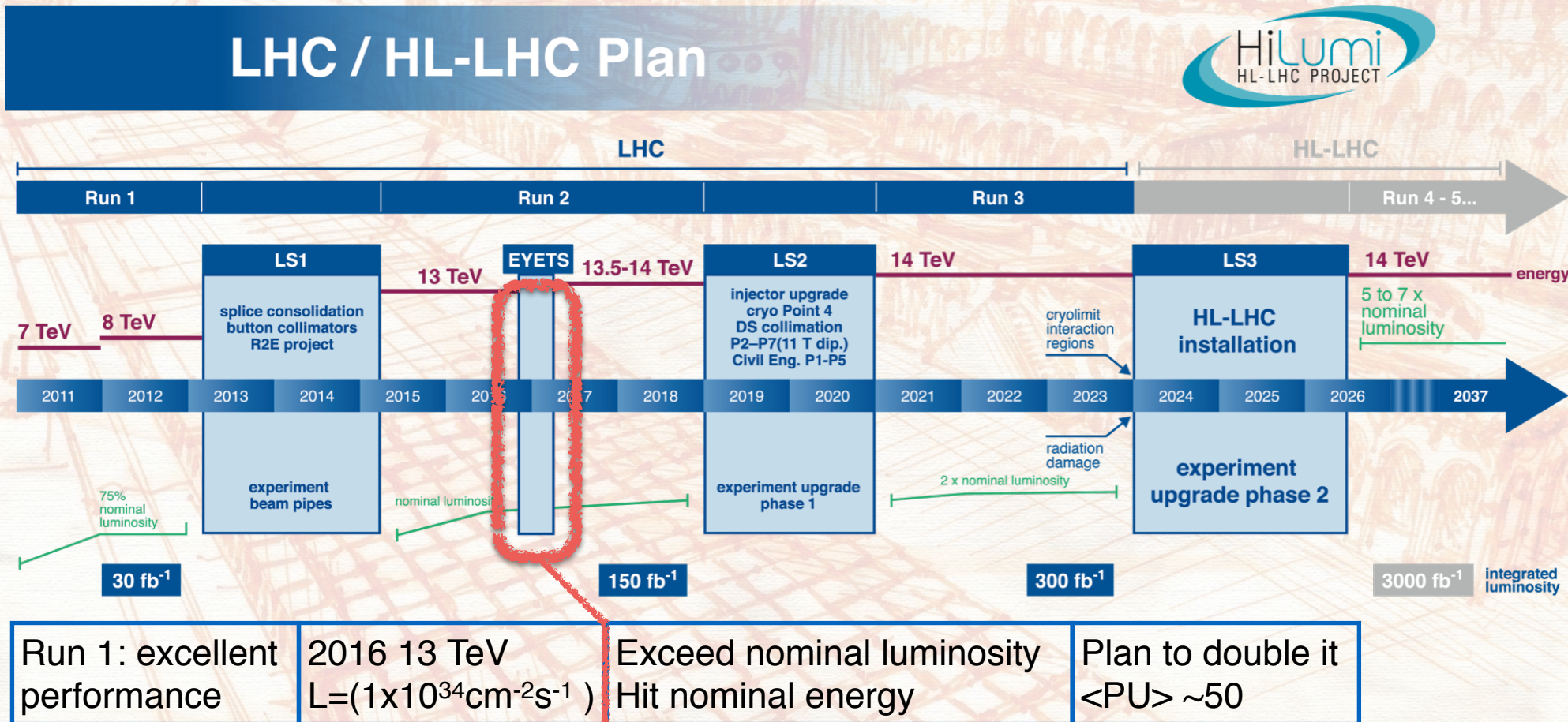
Layout:

- 3 layer in the barrel region (r: 4 - 7 - 11 cm)
- 2 disk for each side in the forward region

Pixel Module Sensor:

- n+ on n silicon bulk $100\mu\text{m} \times 150\mu\text{m}$
- 16 Read Out Chips (ROC) per module
- Each ROC serves a 52×80 pixel matrix
- 56 millions pixel

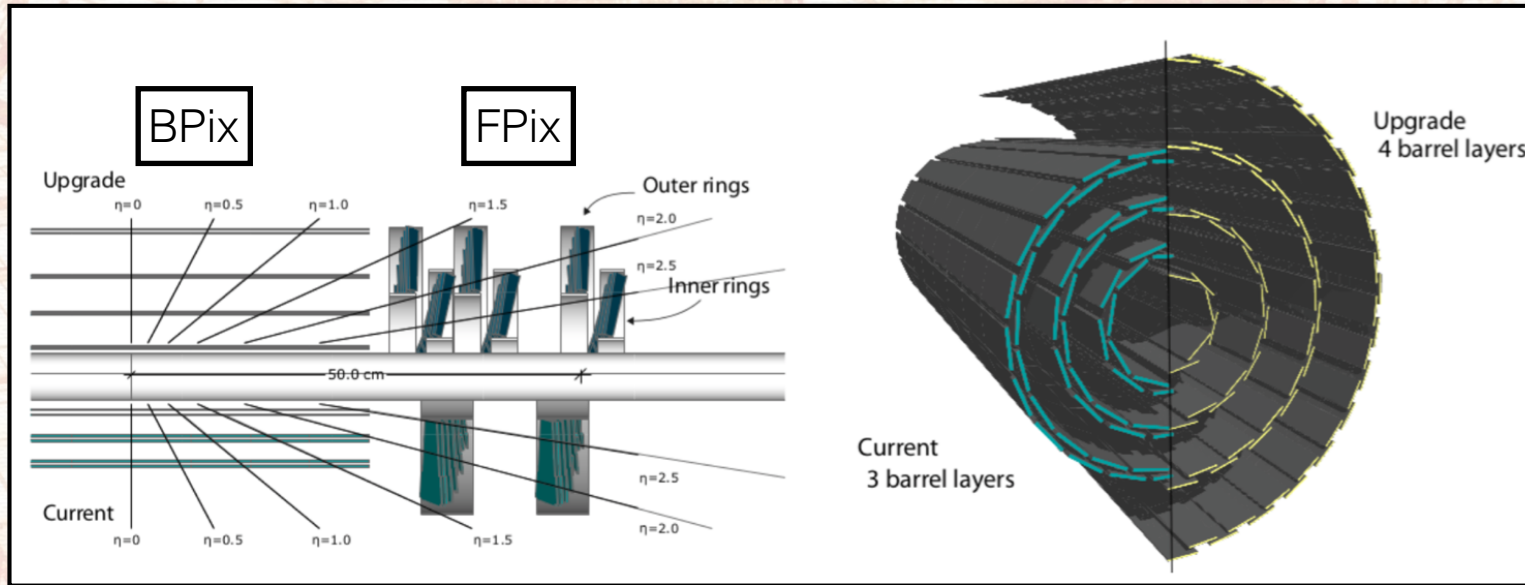
LHC/HL-LHC Plan



CMS Pixel Phase I Upgrade

Will allow to maintain the current level of performance under high luminosity conditions.

The pixel detector upgrade



New digital readout :

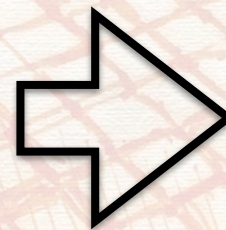
- 40MHz → 400Mbit/s
- increased buffer size

Layout upgrade:

- 4th pixel layer and 2 extra disc for FPIX
- BPix module 768 → 1184
- BPix pixel 48M → 79M

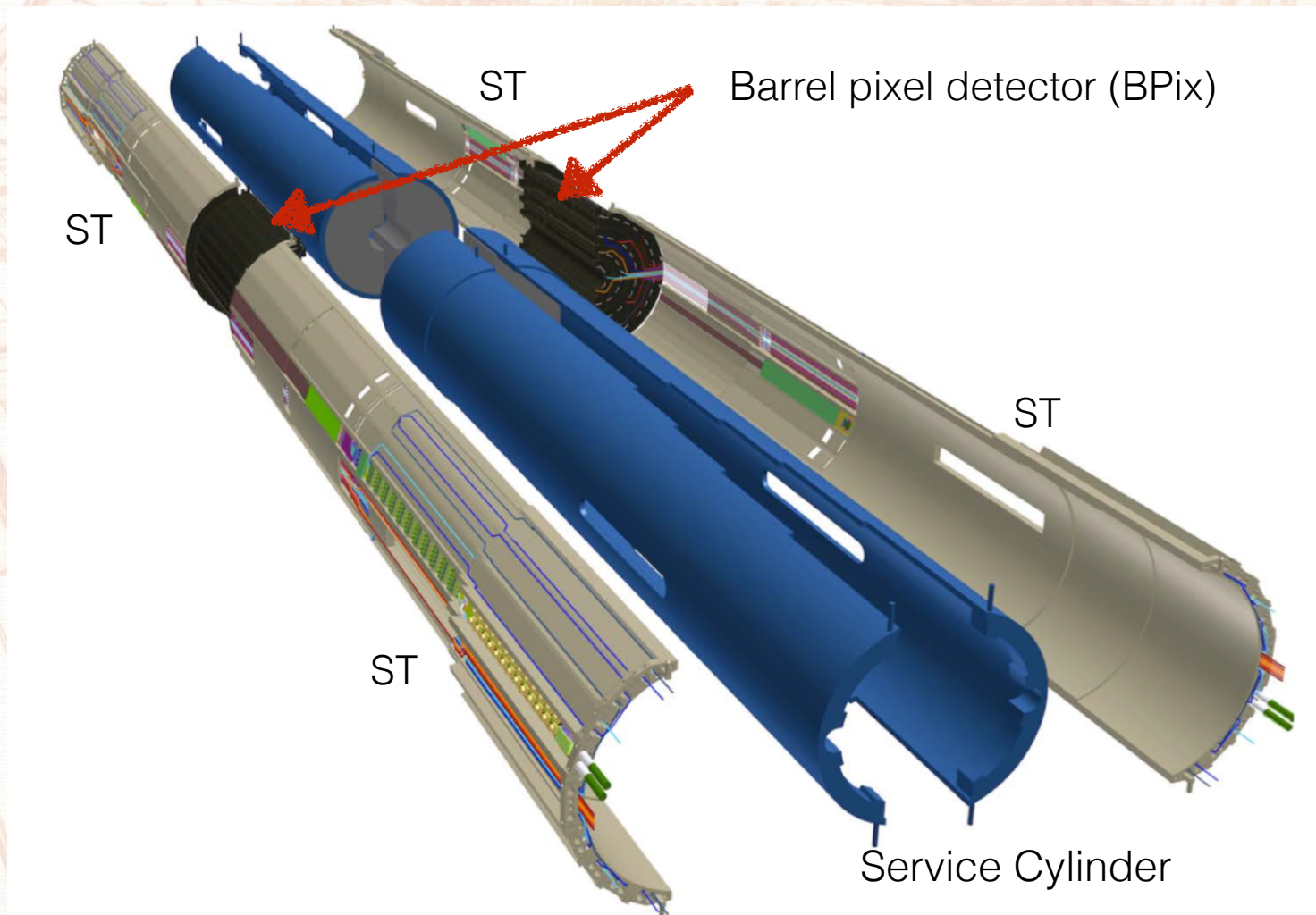
Improved material budget:

- moved electronic to higher η
- lighter mechanic
- CO2 cooling



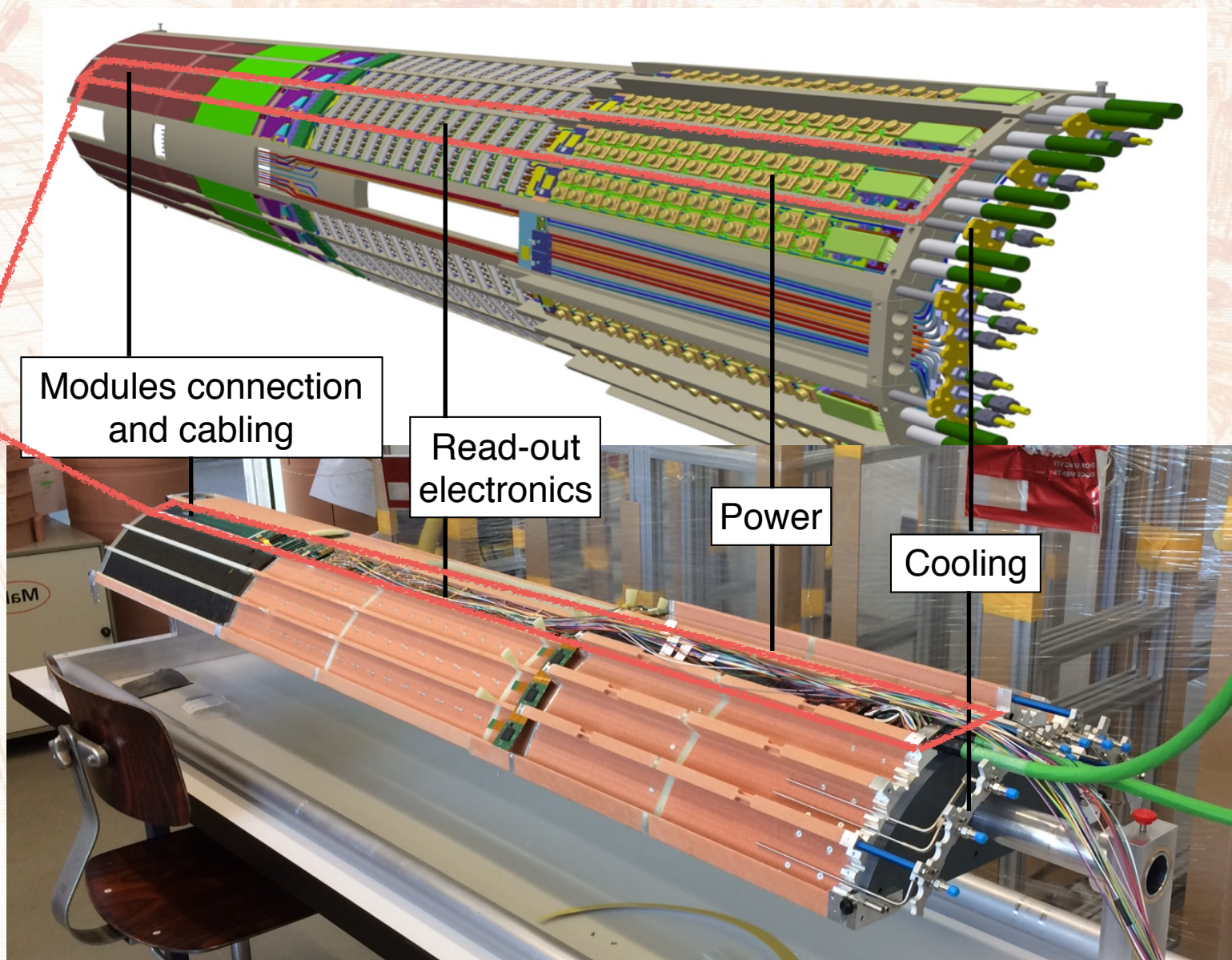
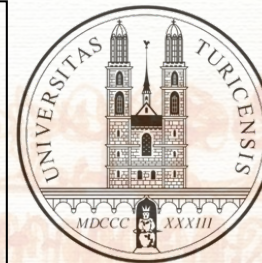
- Reduced dead time and data loss
- Improved track seeding and vertex reconstruction for large pile-up
- Improved IP resolution
- Less multiple scattering and photon conversion

Supply Tube

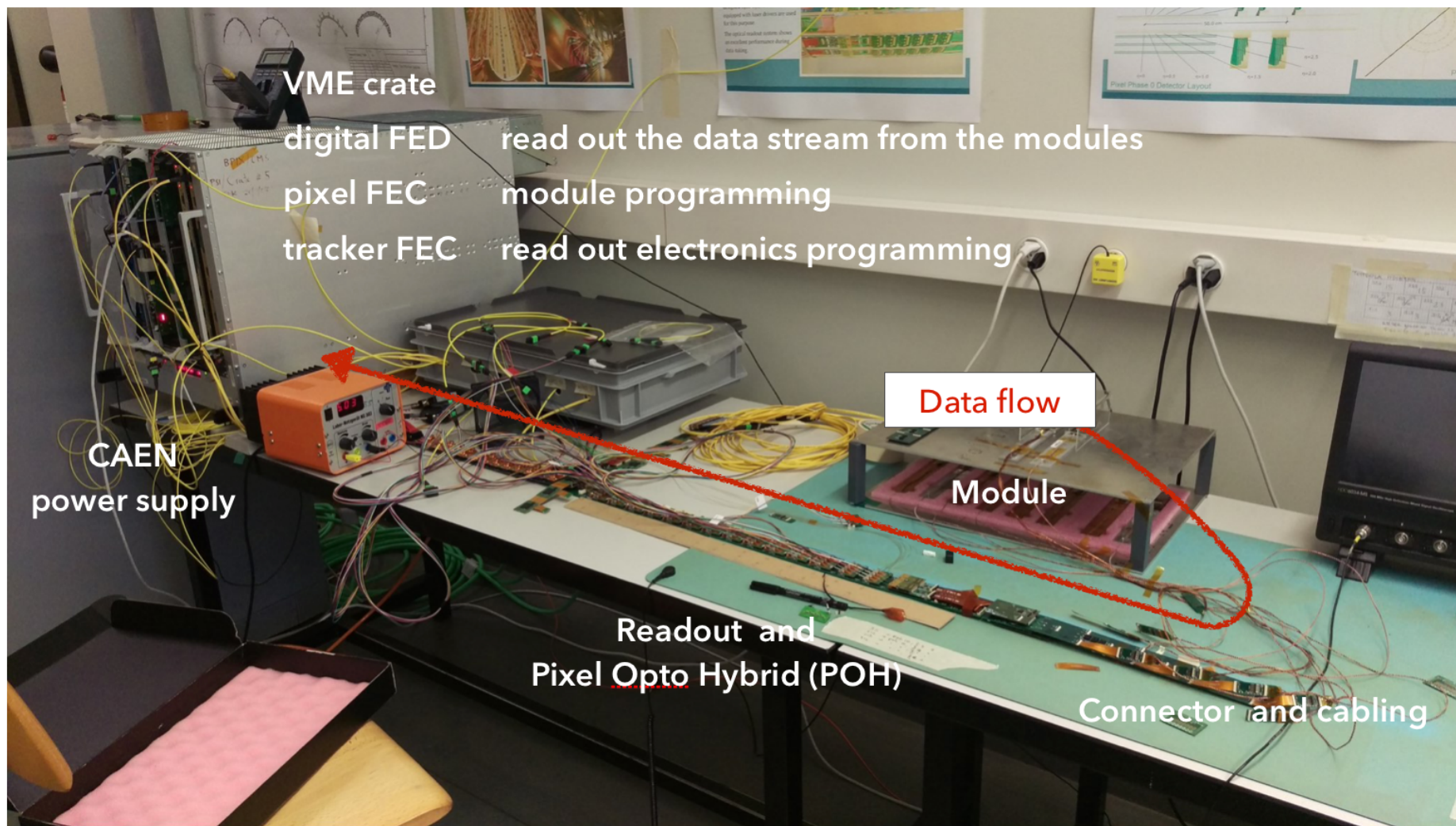


The supply tubes allow the data readout and the programming of the modules and supply power and cooling.

Supply Tube



Test bench at UZH



VME crate

digital FED

pixel FEC

tracker FEC

read out the data stream from the modules

module programming

read out electronics programming

CAEN
power supply

Data flow

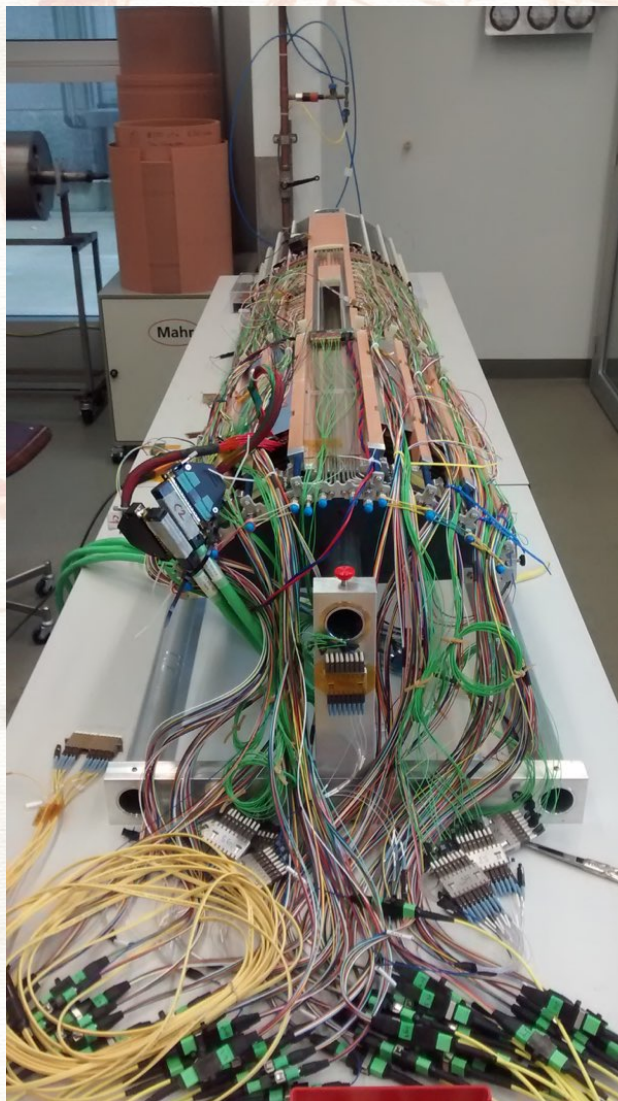
Module

Readout and
Pixel Opto Hybrid (POH)

Connector and cabling

The test stand includes a slice of the CMS pixel DAQ system and all components of the upgraded readout chain together with a number of detector modules.

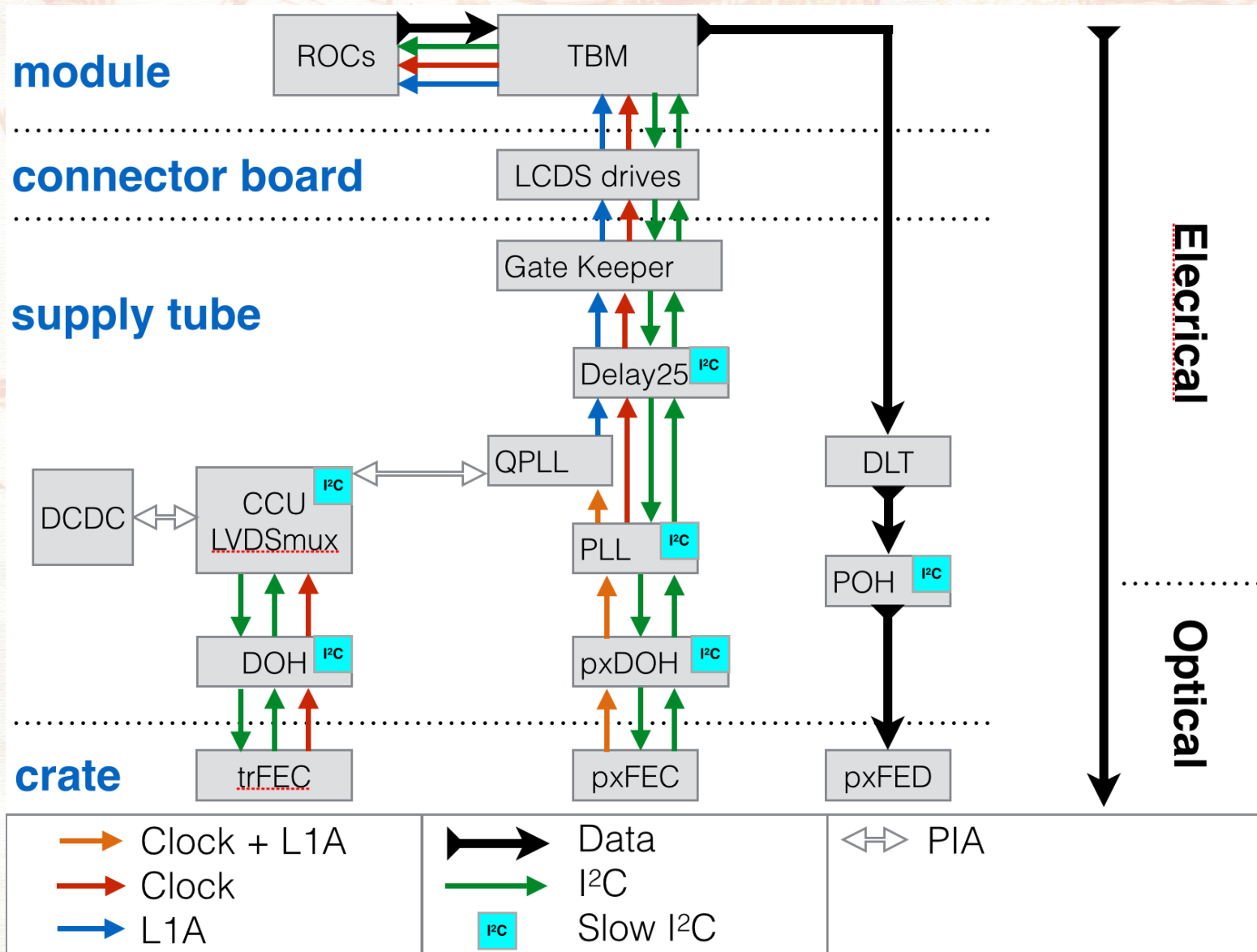
Supply Tube



Testing procedure (room temperature)
High and low voltage distributions
Devices programming and registers readout, functionality tests
POHs laser functionality and fiber connections quality
Communications and programming the modules
Data stream readout
Cold box test



Supply Tube Diagram



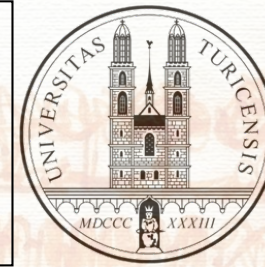
•Three main rows:

- Module
- Supply tube
- Crate/ Counting room

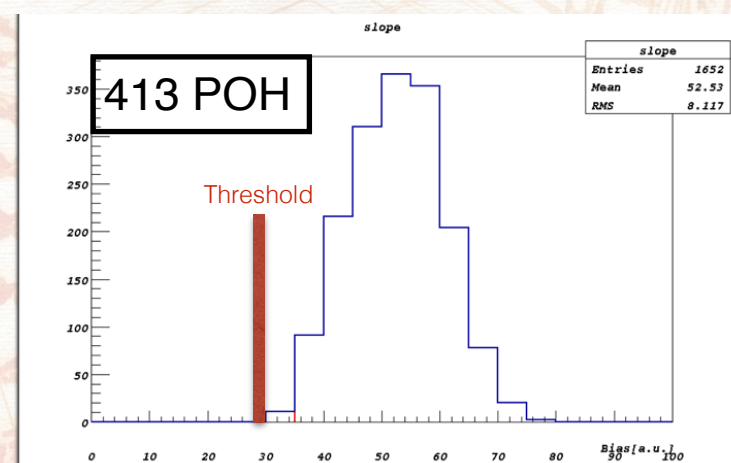
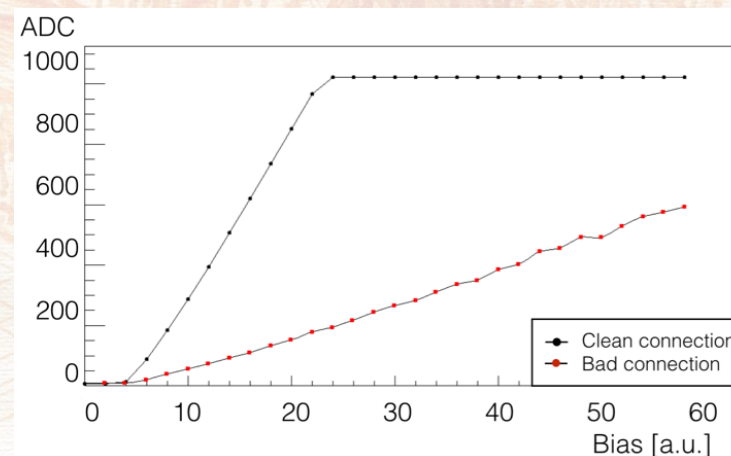
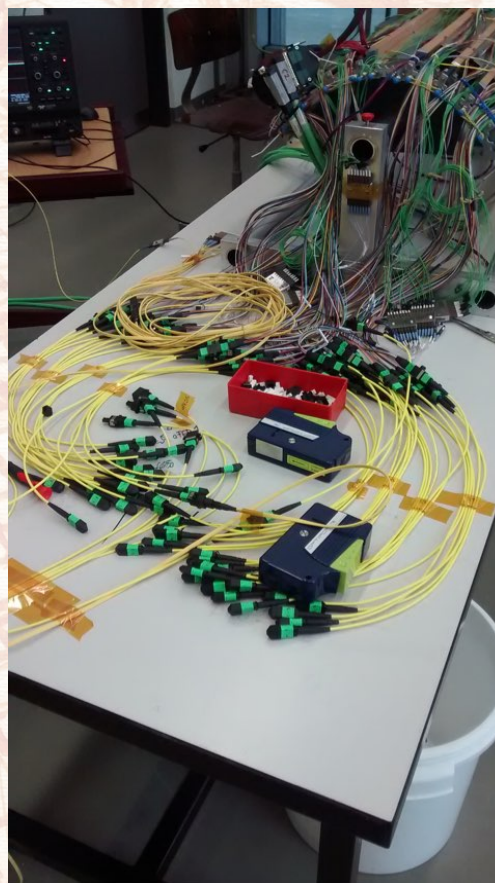
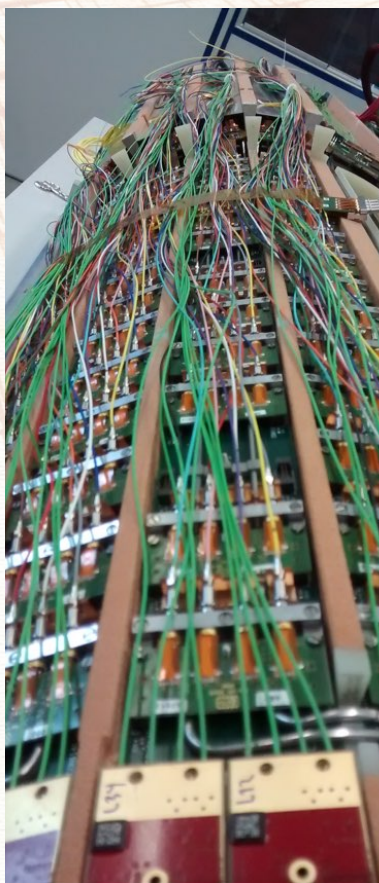
•Three main columns:

- trFEC
- (supply tube devices COM and programmig)
- pxFEC
- (Modules COM and programmig)
- pxFED
- (Data readout)

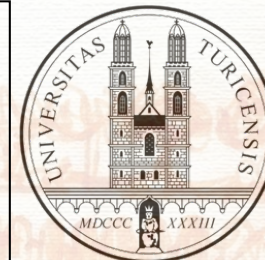
Test POH and optical fiber connections



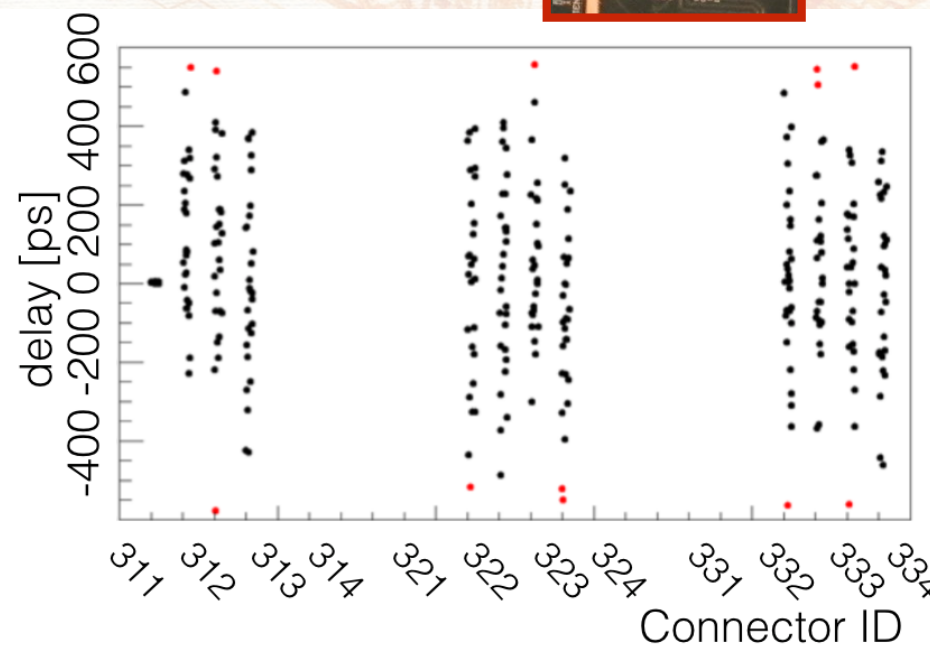
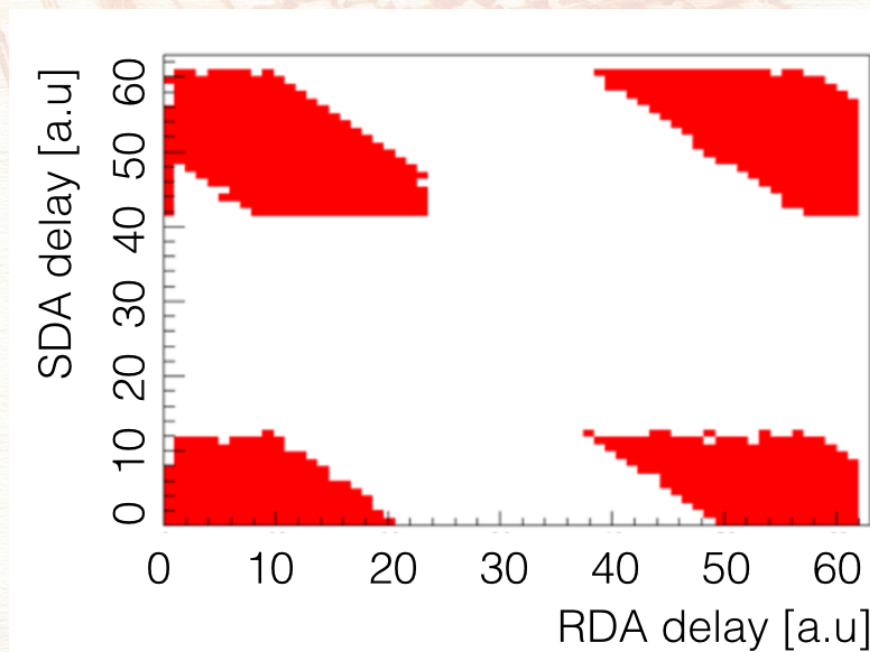
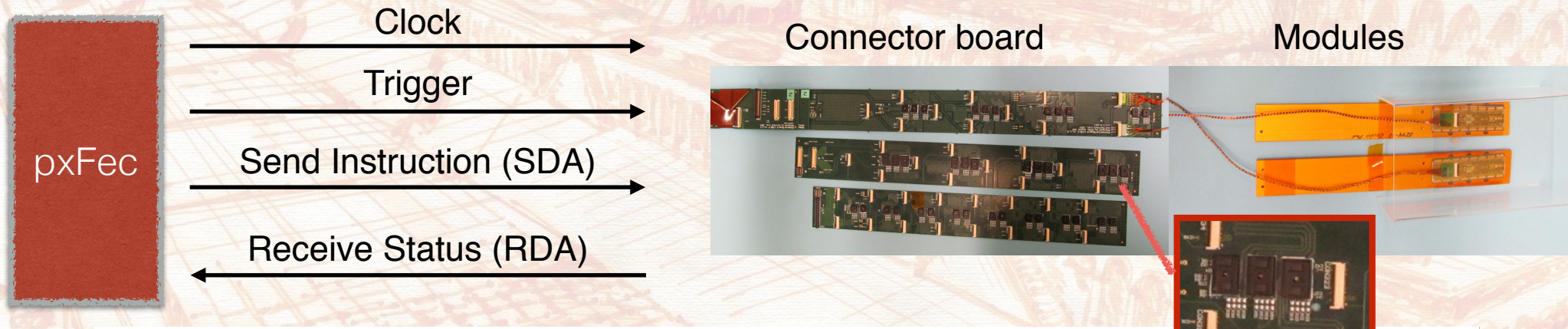
This test aims to check the functionality of the Pixel Opto Hybrid (POH) laser, the quality of the optical fibre connections and the performance of the digital data transmission. The digital data stream coming from the module is converted from an electrical to an optical signal by the POH.



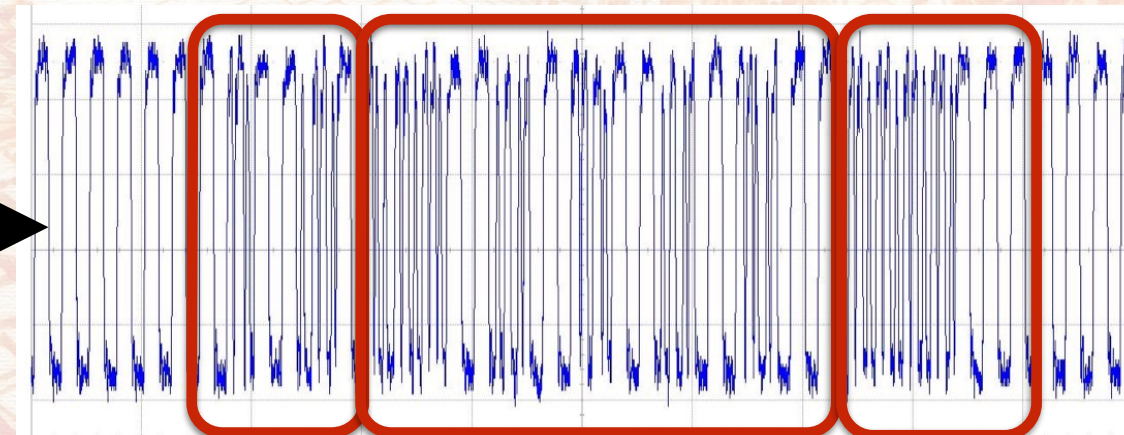
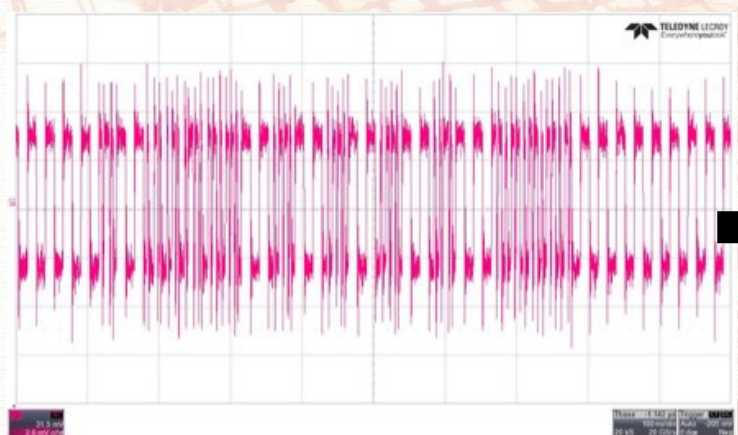
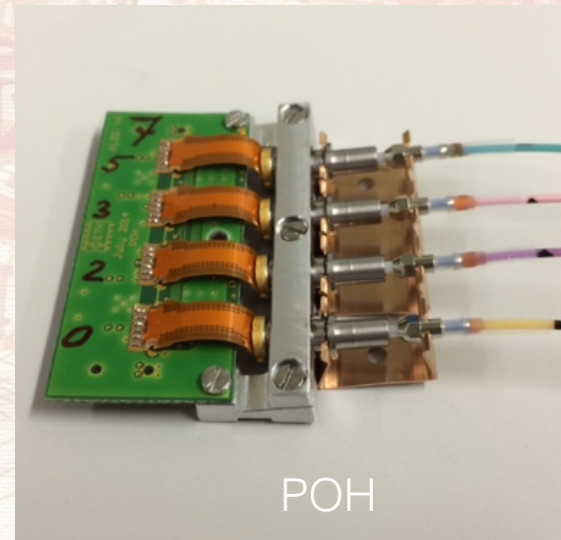
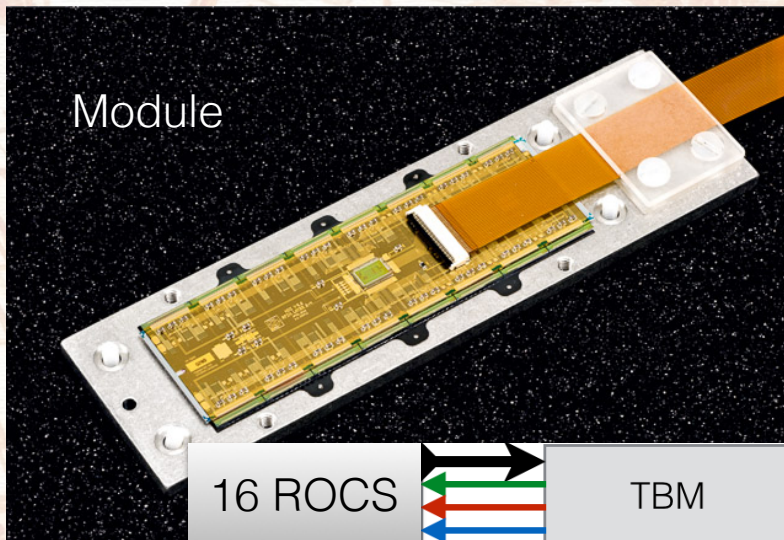
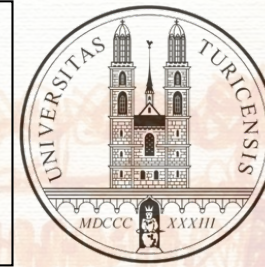
Test Module Programming and trigger delay



First one checks the communications and programming of the modules, then the trigger signal delay among different modules is tuned depending on the module layer, the pseudo-rapidity and cable length.



Test data transmission

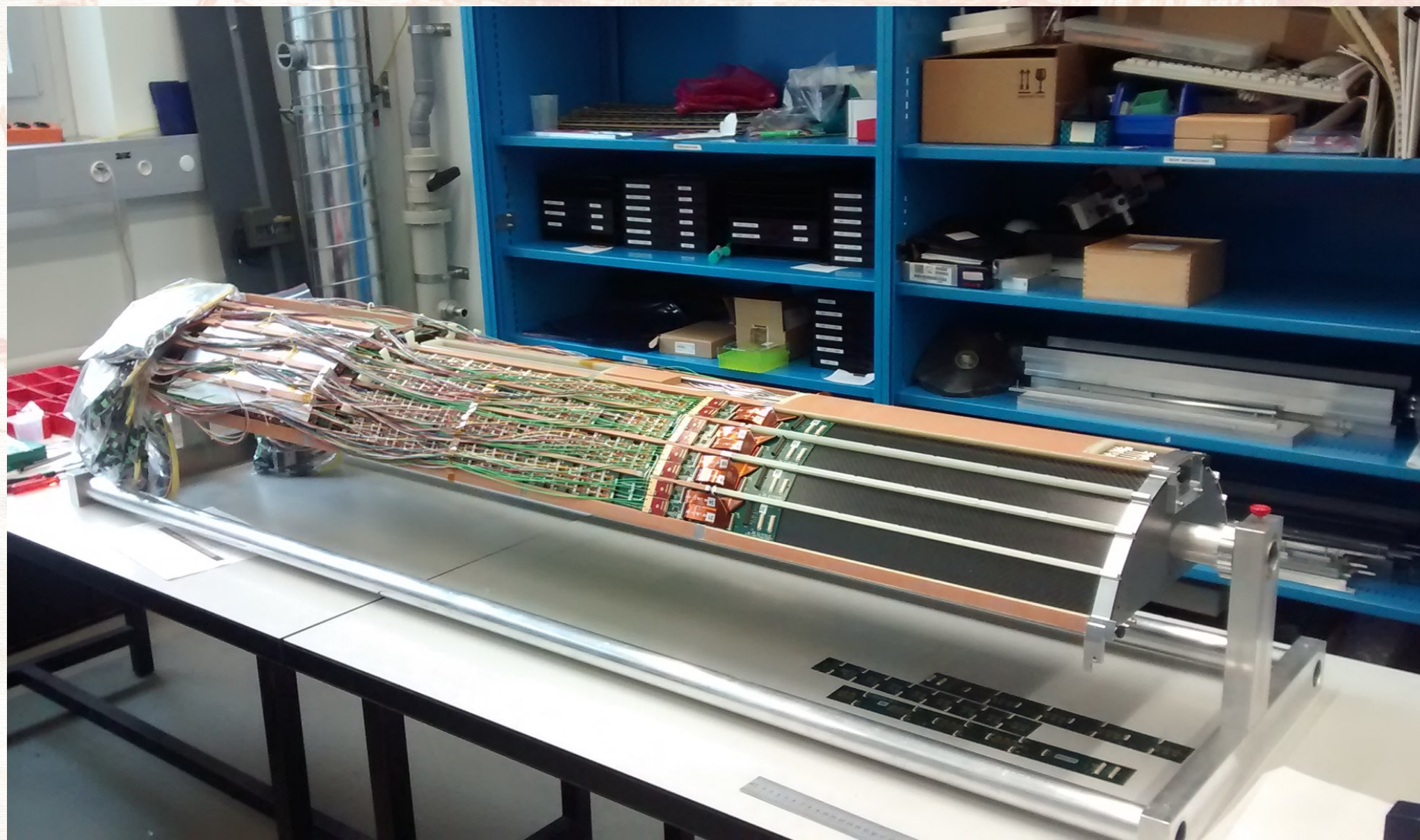


Data (electrical)

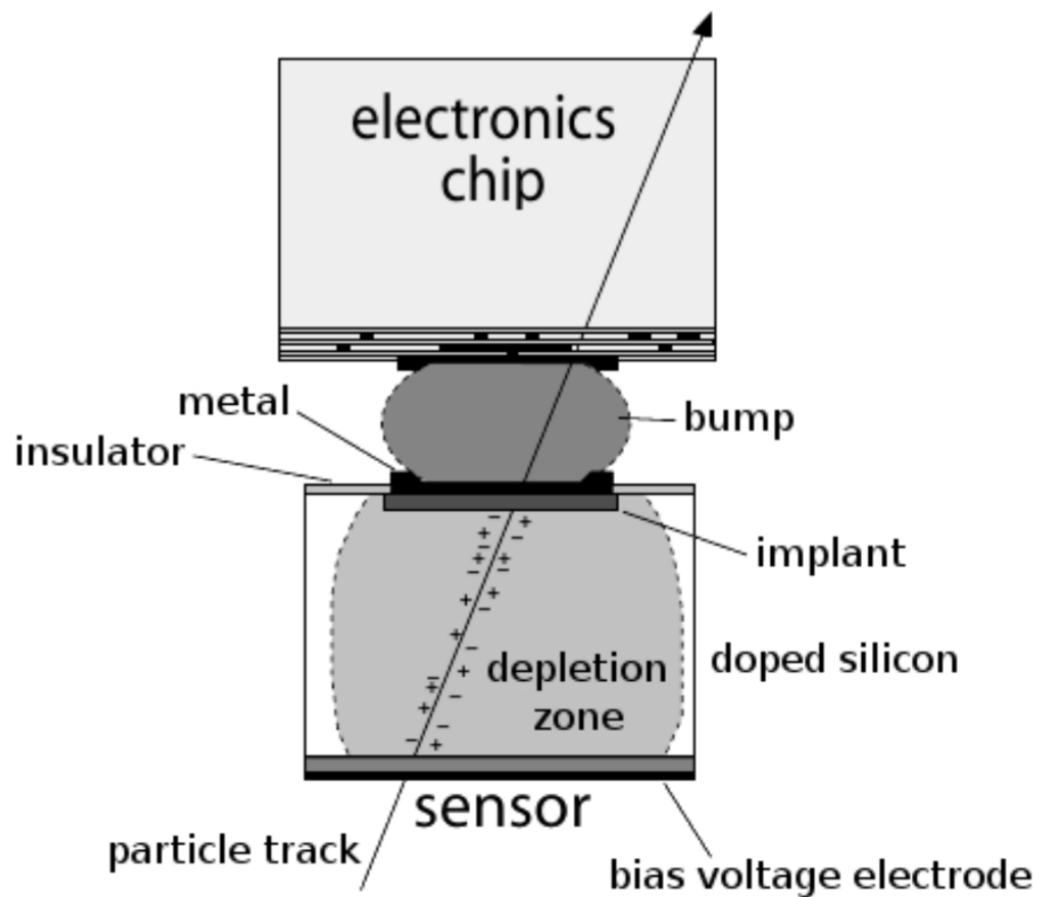


Data (optical) TBM header ROC header TBM trailer

Thanks!



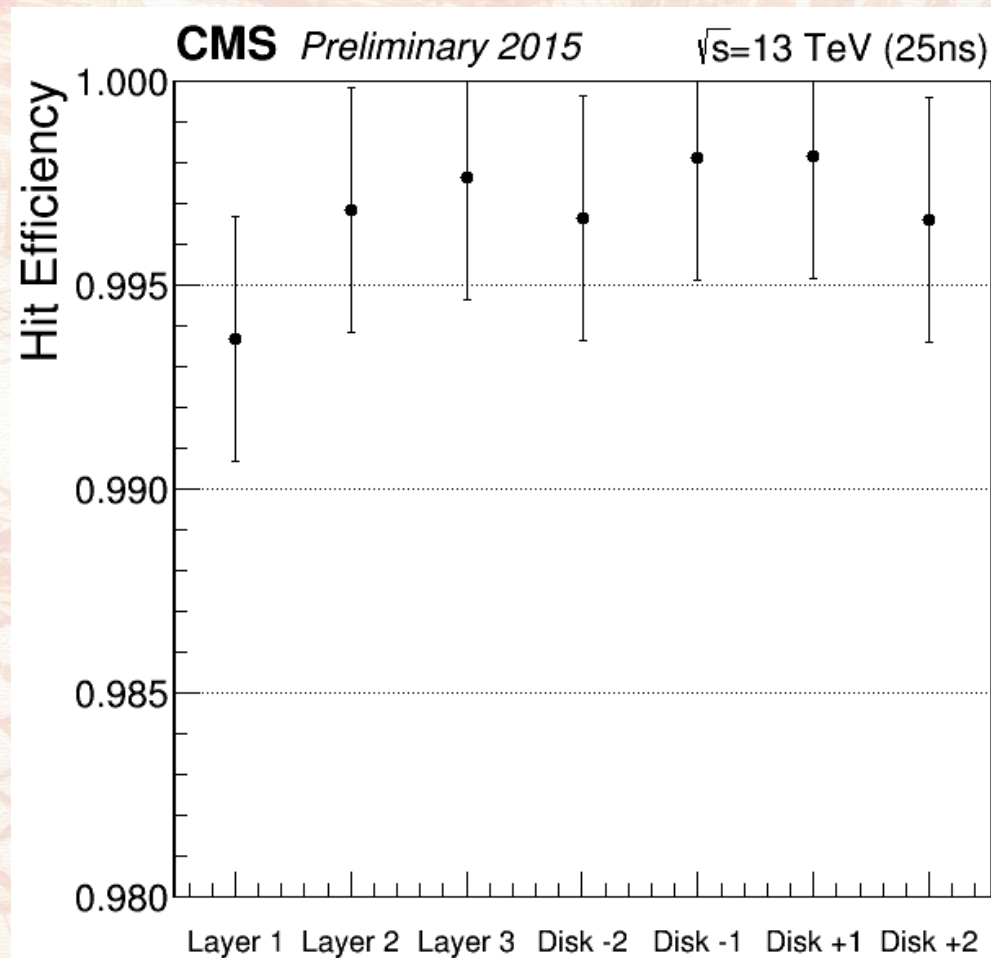
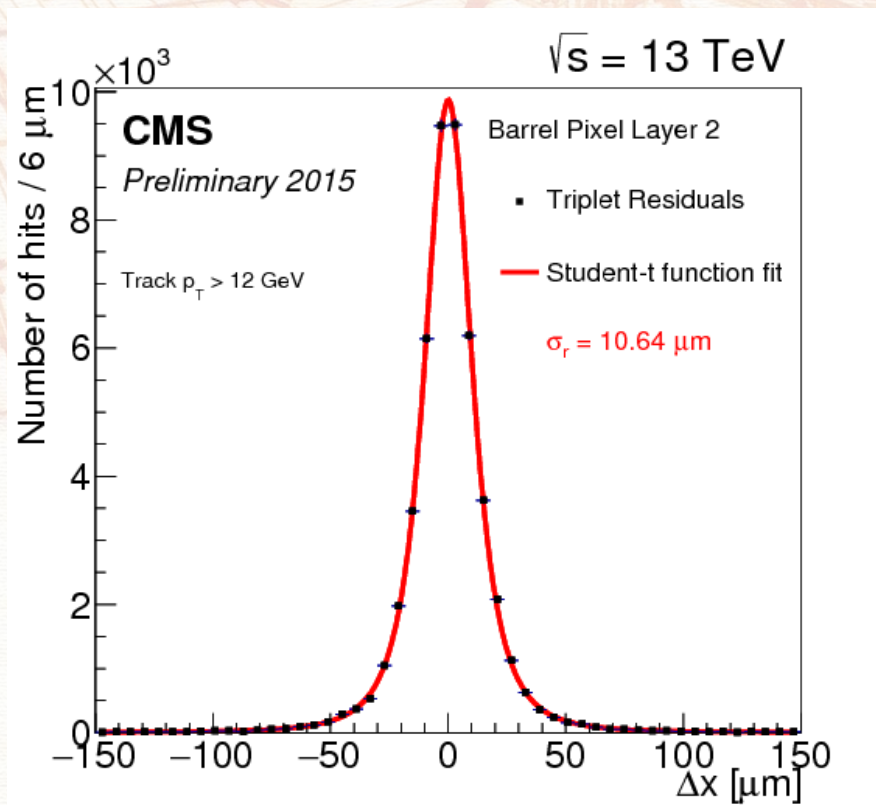
Backup Slides



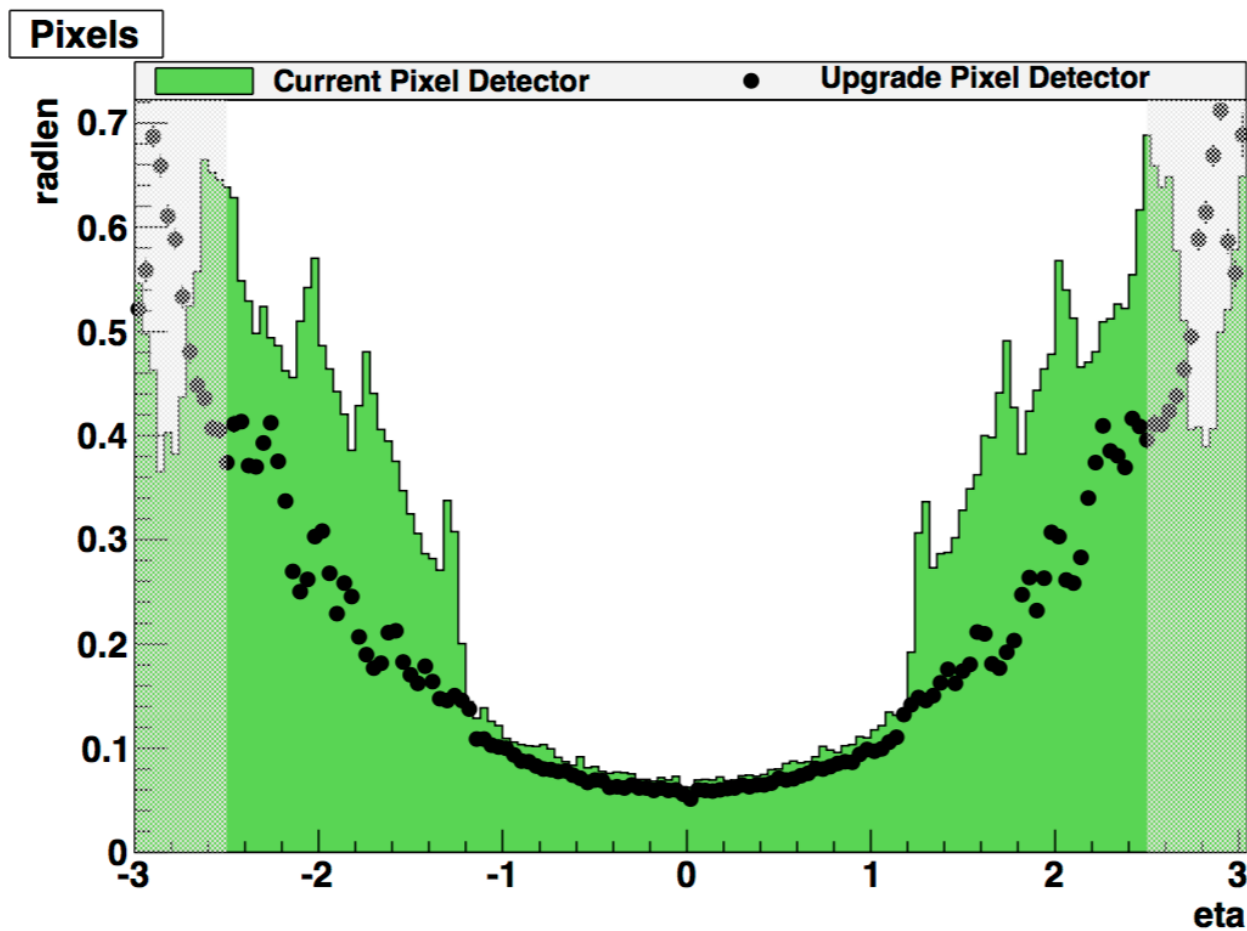
Backup Slides



Hit efficiency and transverse resolution



Backup Slides



Material : rad len vs η

Backup Slides



Sample and Conditions		Tracking Efficiency (%)		Track Fake Rate (%)	
Sample	PU/DL/Cuts	Current	Upgrade	Current	Upgrade
Muon	0/No/Cleanup	97.4	98.1	0.0	0.0
Muon	0/Yes/Cleanup	93.9	97.9	0.0	0.0
Muon	50/No/Cleanup	90.1	94.9	0.22	0.17
Muon	50/Yes/Cleanup	81.5	94.4	0.23	0.17
$t\bar{t}$	0/No/Default	89.6	93.5	0.71	0.40
$t\bar{t}$	0/Yes/Default	85.6	93.2	0.68	0.41
$t\bar{t}$	50/No/Default	84.9	92.2	8.72	5.09
$t\bar{t}$	50/Yes/Default	79.7	92.0	9.49	5.13

Eff/Fake rate for actual and phase I pixel detector
w/wo pile up and ROC dynamic data loss

Supply Tube Testing



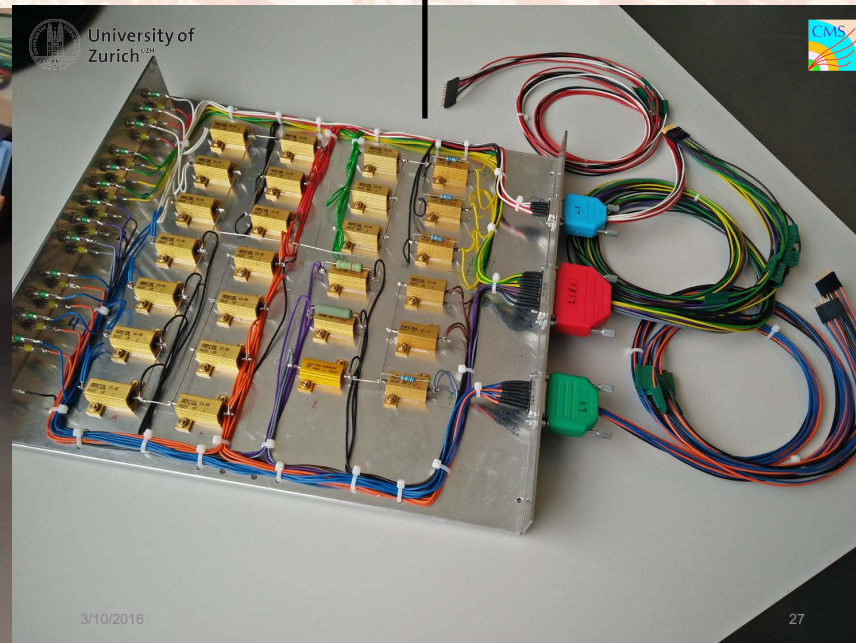
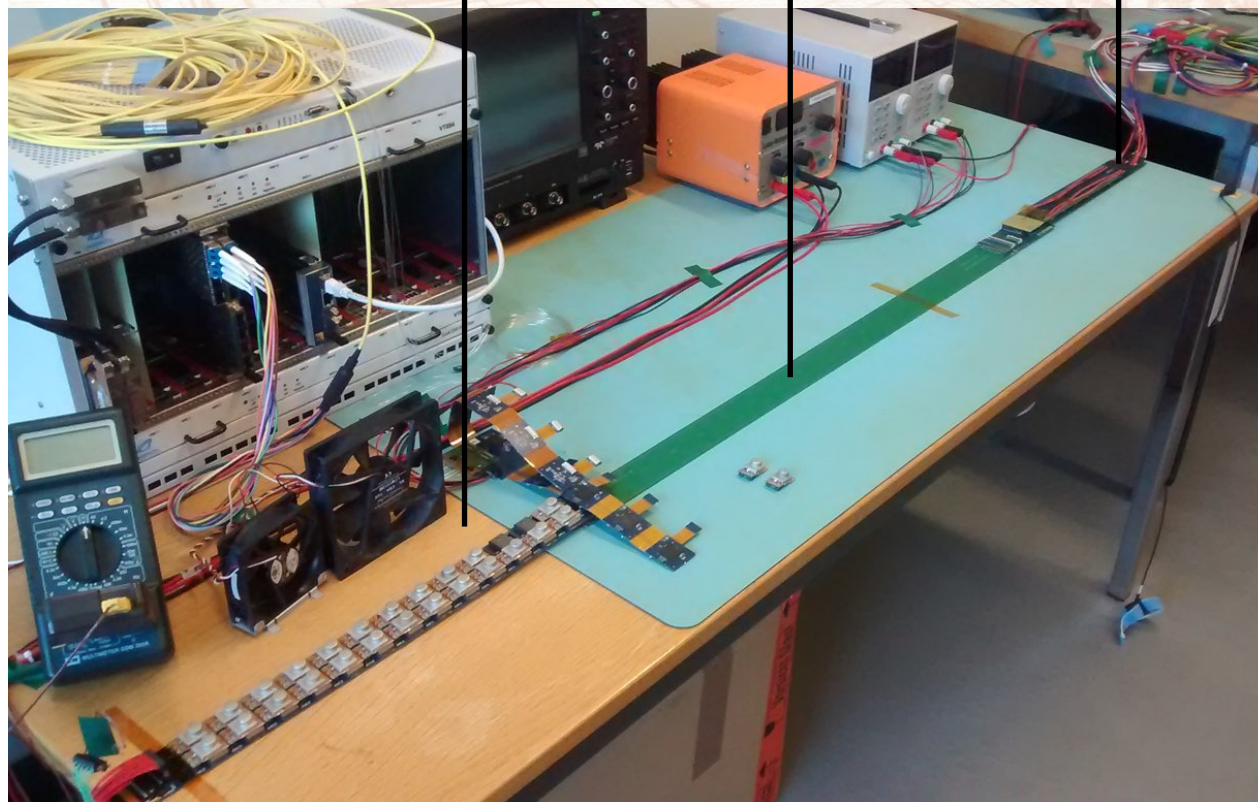
Two independent setups: Electronic test and Power test



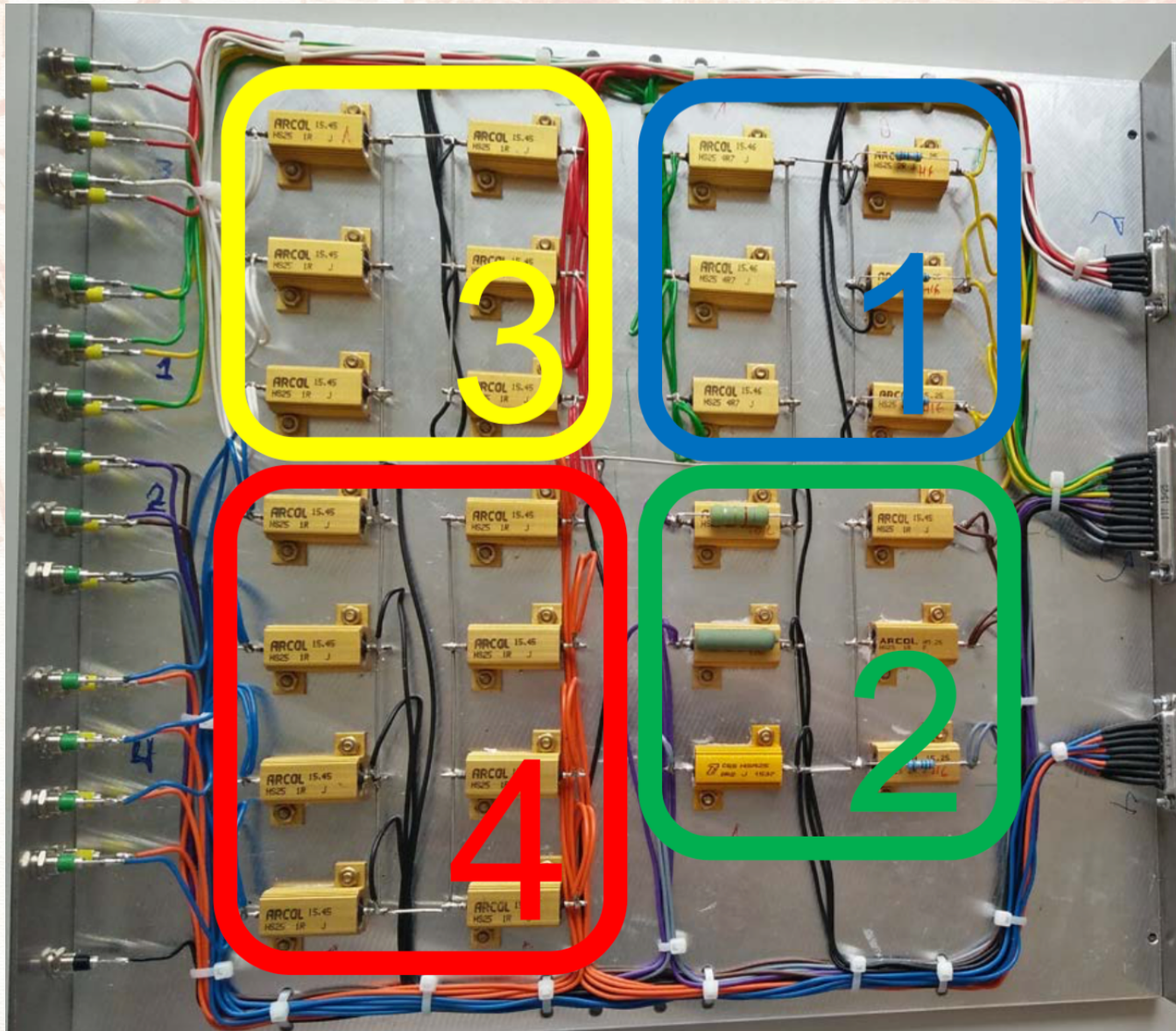
Power Distribution Test



DCDC - Extension Board - Connector Board - Load Board



Load Board



Layer	Mod.	DCDC Pairs
L1	3	3
L2	8	3
L3	12	3
L4	16	4

Design and assembly by Daniel Hernandez Garland

Mechanic on the mandrel

